

ABSTRACT

AN APPARATUS AND METHOD FOR INSPECTING A SEMICONDUCTOR PACKAGE

- 5 There is provided an apparatus and method for inspecting a semiconductor package. The apparatus includes at least one 3D camera positioned at a first angle relative to a normal axis of the semiconductor package; and a light source configured to provide illumination for the at least one 3D camera, the light source being directed at the semiconductor package. The method includes casting a shadow of a bonded wire onto the semiconductor package;
- 10 obtaining a 3D image of the semiconductor package; determining a distance S of the shadow and the bonded wire in the image; and obtaining a wire loop height H of the bonded wire.

Figure 2

